

Product Data Sheet

PoP Paste Indium9.91

Features:

- Eliminates defects due to package-warping
- Air-reflow
- Rheology optimized for both dipping and package-retention
- Designed for use with SAC305 and Sn63/Pb37 alloys
- Excellent solderability
- Long pot life
- Suitable for use down to 0.3mm pitch

Introduction

PoP Paste Indium9.91 is a no-clean solder paste designed for use in package-on-package (0.3mm and larger) applications. **PoP Paste Indium9.91** has a rheology designed to provide a long-lasting dipping process.

Solder Paste Properties

Variable	Value	Test Method
Flux Type Classification:	R0L1	J-STD-004 (IPC-TM-650:2.3.32 and 2.3.33)
Typical Viscosity:	150kcps	ANSI/IPC-TM650
Typical Tack Strength:	40g	ANSI/IPC-TM650
SIR (ohms):	>10 ⁹ after 7 days @ 85°C & 85% RH	ANSI/IPC-TM650
Shelf Life (Sealed):	3 months at ≤10°C	≤10°C
Working Life:	8 hours at room temperature (<30°C, <70%RH)	ICA test method

All information is for reference only. Not to be used as incoming product specifications.

Alloys

PoP Paste Indium9.91 is available with SAC305 (96.5Sn/3.0Ag/0.5Cu) and Sn63 (63.0Sn/37.0Pb). The following table shows the alloy properties.

Indalloy® Number	Alloy Composition	Melting Point °C		Melting Point °F		Density g/cm ³	Tensile Strength psi	Young's Modulus psi* 10 ⁶	Elongation %
		Liquidus	Solidus	Liquidus	Solidus				
256	96.5Sn/3.0Ag/0.5Cu	220	217	428	423	7.40	7200	2.41	19.3
106	63.0Sn/37.0Pb	183	183	361	361	8.40	7500	4.35	37.0

Application

Solder paste is applied to the spheres in a doctor-bladed dipping process (Figure 1).

- Typical package-on-package applications only need dipping to 25-45% of the sphere height

Care must be taken to avoid contaminating the bottom of the package itself with PoP paste, as this may cause bridging defects.

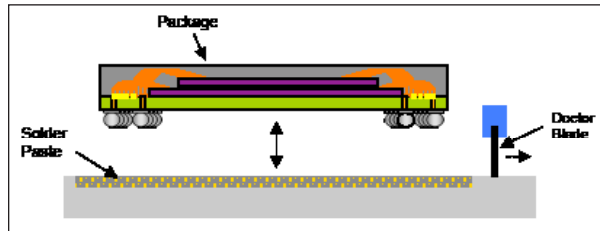


Figure 1. Dipping process.

Consistent solder paste volumes are reproducibly attained from dipping 0.3mm or higher pitch packages in the **PoP Paste Indium9.91**.

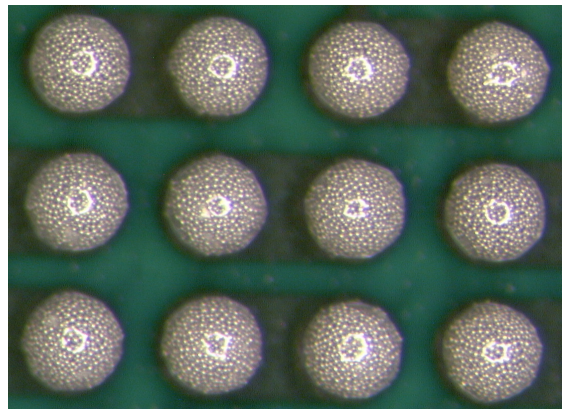


Figure 2. Bottom view of 0.4mm pitch BGA package after dipping in PoP Paste Indium9.91.

OVER→

Form No. 98850 R1

www.indium.com

askus@indium.com

ASIA: Singapore, Cheongju: +65 6268 8678
 CHINA: Suzhou, Shenzhen, Liuzhou: +86 (0)512 628 34900
 EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400
 USA: Utica, Clinton, Chicago: +1 315 853 4900



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PoP Paste Indium9.91

Cleaning

Although designed as a no-clean material, the residue from the **PoP Paste Indium9.91** may be cleaned using commercially available cleaning solutions.

Packaging

PoP Paste Indium9.91 is available in airless (bubble-free) packaging. For automated dispense applications:

- 75g (30cc) syringes are standard
- Other packaging may be available to meet specific requirements. Consult with Indium Corporation Sales or Technical Service staff for details.

Storage and Handling

PoP Paste Indium9.91 syringes and cartridges should be stored tip down at 10°C for a maximum of 6 months. **PoP Paste Indium9.91** should be allowed to stand for at least 4 hours at room temperature before using.

Once removed from cold storage, the solder paste in a sealed syringe may remain at room temperature for up to 7 days before usage and during usage. However, once outside the syringe, its working life is estimated to be 8 hours, and may be less under high temperature (>25 °C) and humidity (>70%RH) conditions.

The paste should not be subjected to multiple cold/heat cycles or viscosity changes and/or flux separation may occur.

Technical Support

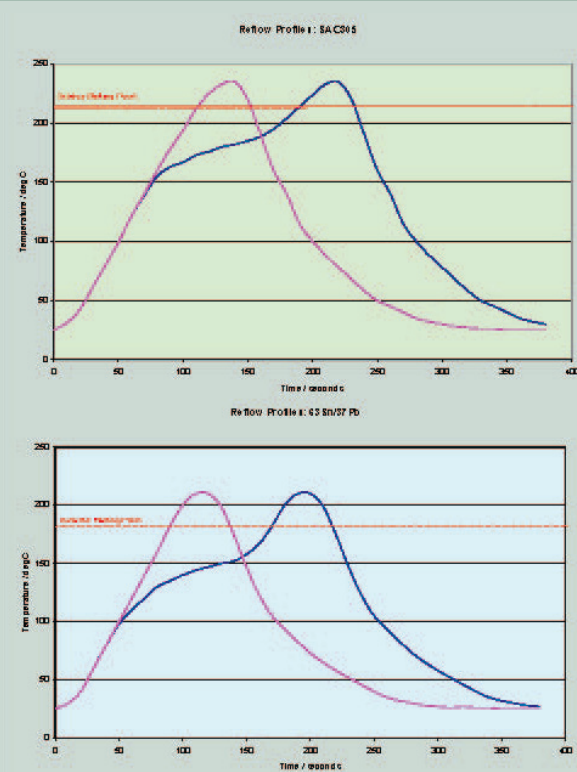
Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of materials science and semiconductor packaging process applications.

Material Safety Data Sheets

The MSDS for this product can be found online at <http://www.indium.com/msds>

Reflow

Recommended Profile:



Peak reflow temperature will vary with the alloy type. A short preheat (140-150 °C for 63Sn and 150-160 °C for SAC305) for less than 45 seconds may be used to reduce solderballing caused by excess paste. The profile should ideally be a linear ramp at 1-2 °C/second up to 20-30 °C above solidus temperature, with a rapid cool down afterwards, and a minimum time above liquidus of 20 seconds.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance

of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.

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askus@indium.com

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